

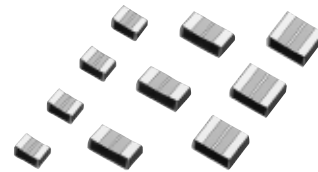
Stacked Metallized Plastic Film Chip Capacitor

Type : **ECPU(A)**

Stacked dielectric and inner electrode with simple mold-less construction

■Features

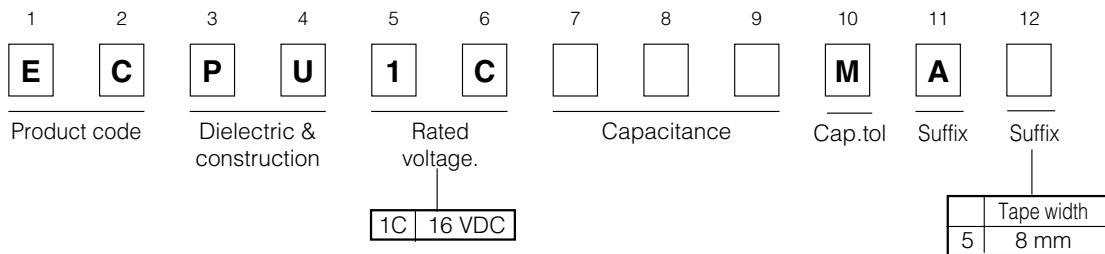
- Low ESR
- Max. capacitance values 1.0 μF
- Smallest package size in film capacitors 3225/1.0 μF
- For reflow soldering
- RoHS directive compliant



■Recommended Applications

- Noise suppressor
- Coupling

■Explanation of Part Numbers

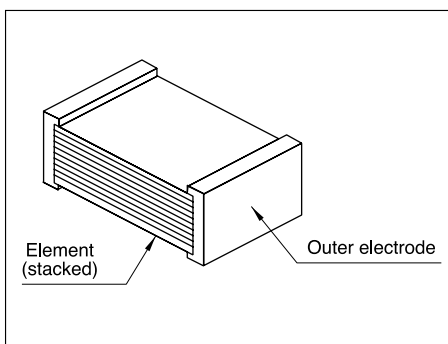


■Specifications

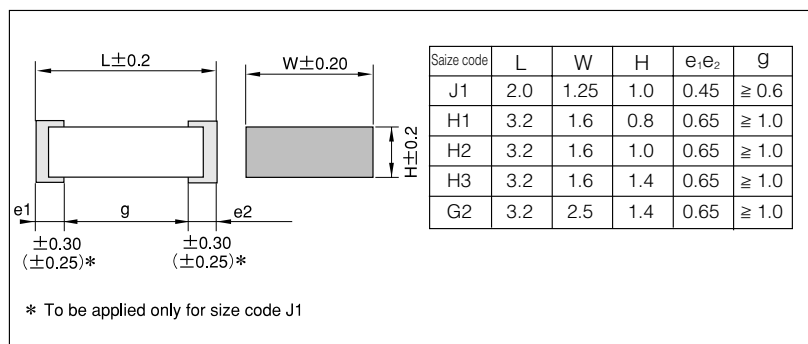
Category temp. range (Including temperature-rise on unit surface)	- 40 °C to + 85 °C
Rated voltage	16 VDC
Capacitance range	0.10 μF to 1.0 μF (E6)
Capacitance tolerance	$\pm 20\%$ (M)
Dissipation factor ($\tan\delta$)	$\tan\delta \leq 1.5\%$ (20 °C, 1 kHz)
Withstand voltage	Between terminals: Rated volt (VDC) $\times 175\%$ 1 s to 5 s
Insulation resistance (IR)	C $\leq 0.33 \mu\text{F}$: IR $\geq 1000 \text{ M}\Omega$ (20 °C, 10 VDC, 60 s) C $> 0.33 \mu\text{F}$: IR $\geq 300 \text{ M}\Omega \cdot \mu\text{F}$ (20 °C, 10 VDC, 60 s)
Soldering conditions	Reflow soldering : 240 °C max. and 30 sec max. at more than 220 °C (Temp. at cap. surface)

* In case of applying voltage in alternating current (50 Hz or 60 Hz sine wave) to a capacitor with DC rated voltage, please refer to the page of "Permissible voltage (R.M.S) in alternating current corresponding to DC rated voltage".

■Construction



■Dimensions in mm (not to scale)



■Taping Specification for Automatic Mounting

Refer to the page of taping specifications.

■Rating, Dimensions & Quantity/Reel

Part No.	Cap. (μF).	Dimensions (mm)				Quantity
		L	W	H	Size Code	
ECPU1C104MA5	0.1	2.0	1.25	1.0	J1	3000
ECPU1C154MA5	0.15	3.2	1.6	0.8	H1	
ECPU1C224MA5	0.22	3.2	1.6	0.8	H1	
ECPU1C334MA5	0.33	3.2	1.6	1.0	H2	
ECPU1C474MA5	0.47	3.2	1.6	1.4	H3	2000
ECPU1C684MA5	0.68	3.2	1.6	1.4	H3	
ECPU1C105MA5	1.0	3.2	2.5	1.4	G2	

■Recommended for Land Dimensions (mm)

Size Code	Land dimensions for reflow soldering		
	A	B	C
J1	0.8	2.4	1.1
H1	1.8	3.6	1.4
H2	1.8	3.6	1.4
H3	1.8	3.6	1.4
G2	1.8	3.6	2.3